

Part Number: KPED-3528SEC

Super Bright Orange

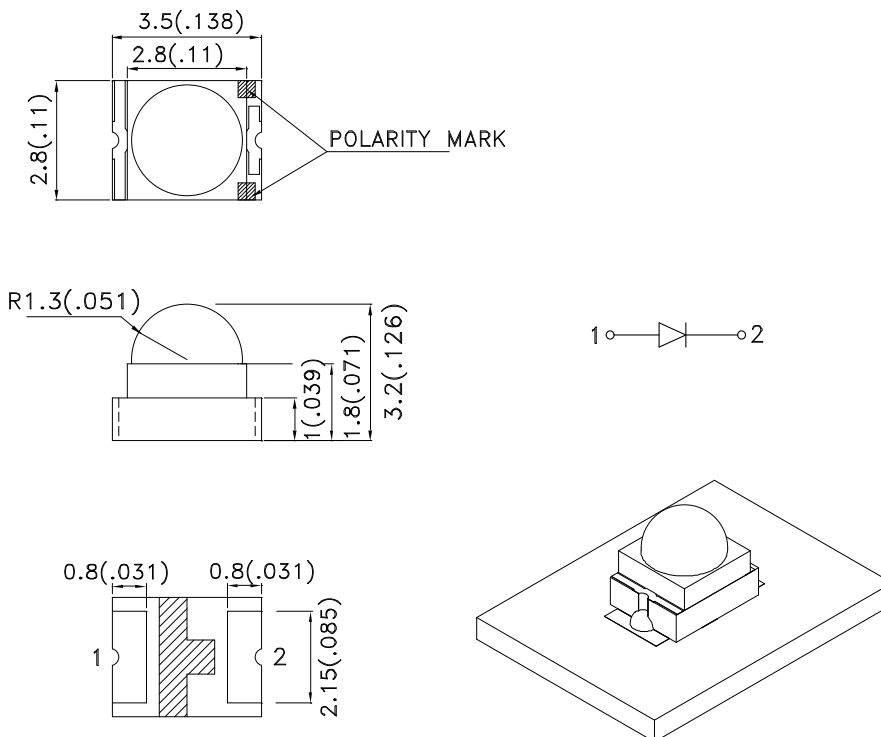
Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- IDEAL FOR BACKLIGHTING.
- AVAILABLE ON TAPE AND REEL.
- PACKAGE: 500PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.

Description

The Super Bright Orange device is made with InGaAlP (on GaAs substrate) light emitting diode chip.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ unless otherwise noted.
3. Specifications are subject to change without notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KPED-3528SEC	Super Bright Orange (InGaAlP)	WATER CLEAR	380	700	40°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	IF=20mA
C	Capacitance	Super Bright Orange	30		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2	2.5	V	IF=20mA
IR	Reverse Current	Super Bright Orange		10	uA	VR=5V

Notes:

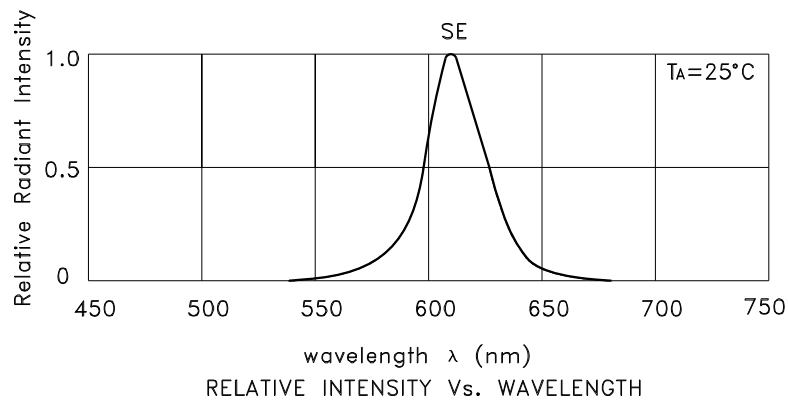
- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

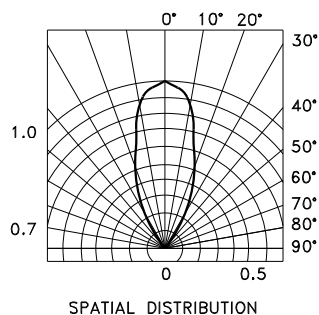
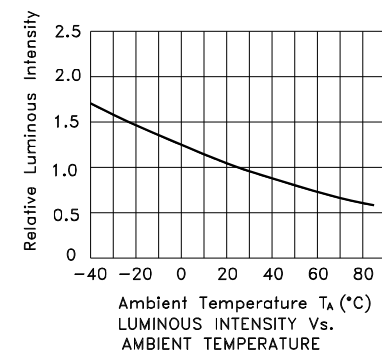
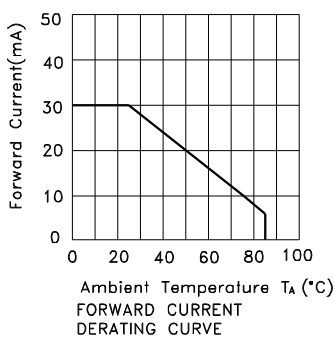
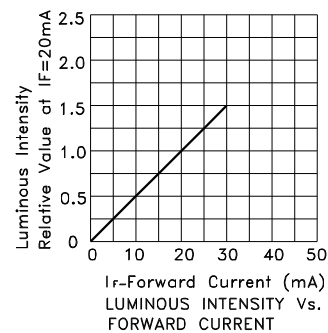
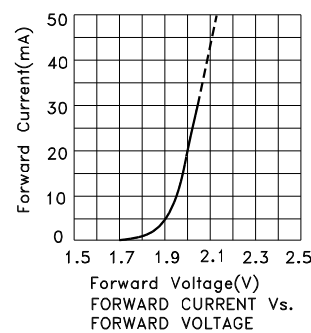
Parameter	Super Bright Orange	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

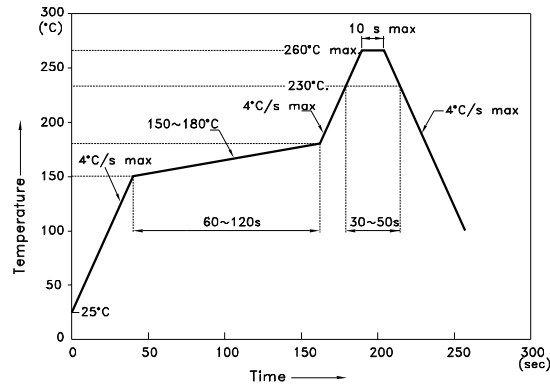


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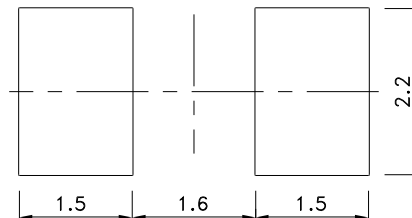
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Tape Specifications (Units : mm)

